



TGD N-Channel Enhancement Mode Power MOSFET

Description

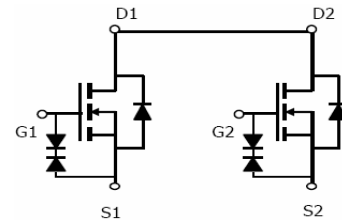
The TGD2008E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected.

General Features

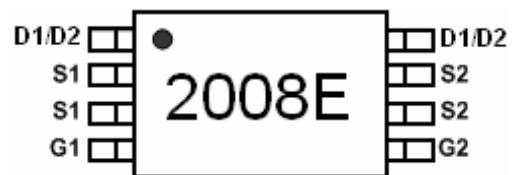
- $V_{DS} = 20V, I_D = 6A$
 $R_{DS(ON)} < 30m\Omega @ V_{GS}=2.5V$
 $R_{DS(ON)} < 24m\Omega @ V_{GS}=4.5V$
ESD Rating: 2000V HBM
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

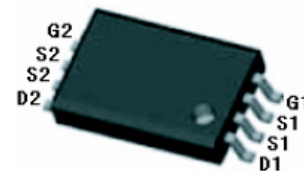
- PWM application
- Load switch



Schematic diagram



pin assignment



TSSOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2008E	TGD2008E	TSSOP-8	Ø330mm	12mm	3000 units

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	6	A
Drain Current-Pulsed (Note 1)	I_{DM}	30	A
Maximum Power Dissipation	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^{\circ}C$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	83.3	$^{\circ}C/W$
--	-----------------	------	---------------

Electrical Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20		-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA



Parameter	Symbol	Condition	Min	Typ	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V	-	-	±10	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.45	0.7	1.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =6A	-	17	24	mΩ
		V _{GS} =2.5V, I _D =5A	-	22	30	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =6A	-	20	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{ISS}		-	650	-	PF
Output Capacitance	C _{OSS}	V _{DS} =10V,V _{GS} =0V, F=1.0MHz	-	140	-	PF
Reverse Transfer Capacitance	C _{RSS}					
			-	60	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V,R _L =1. 5Ω V _{GS} =5V,R _{GEN} =3Ω	-	0.5		nS
Turn-on Rise Time	t _r		-	1		nS
Turn-Off Delay Time	t _{d(off)}		-	12		nS
Turn-Off Fall Time	t _f		-	4		nS
Total Gate Charge	Q _g	V _{DS} =10V,I _D =6A, V _{GS} =4.5V	-	8		nC
Gate-Source Charge	Q _{gs}		-	2.5	-	nC
Gate-Drain Charge	Q _{gd}		-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	6	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

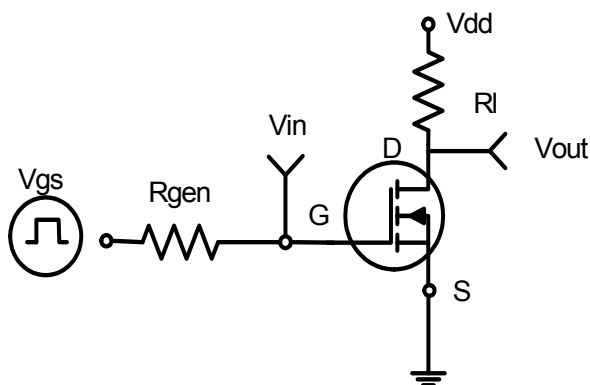


Figure 1: Switching Test Circuit

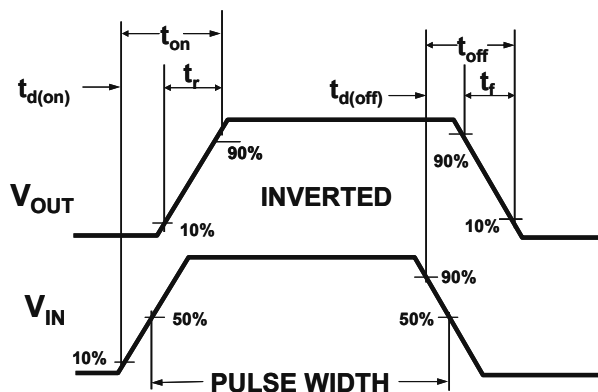


Figure 2: Switching Waveforms

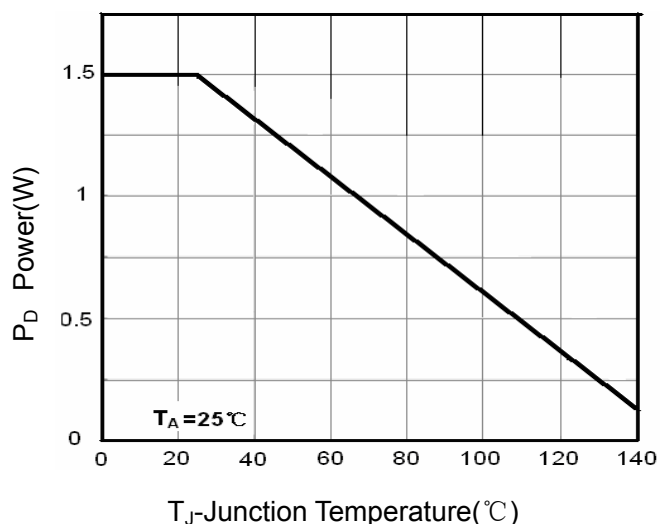


Figure 3 Power Dissipation

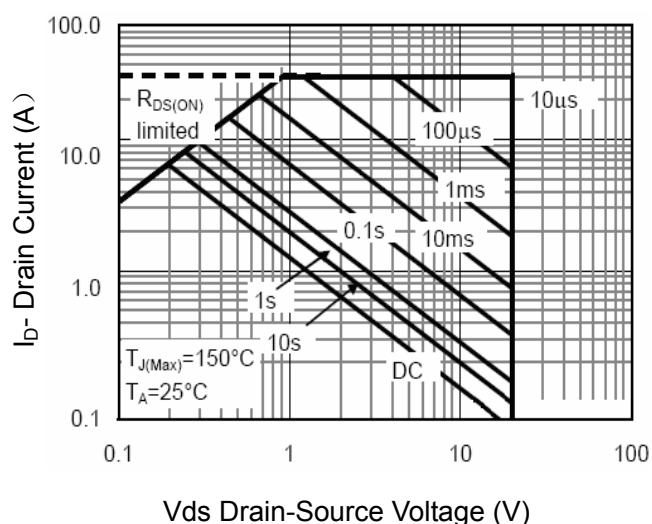


Figure 4 Safe Operation Area

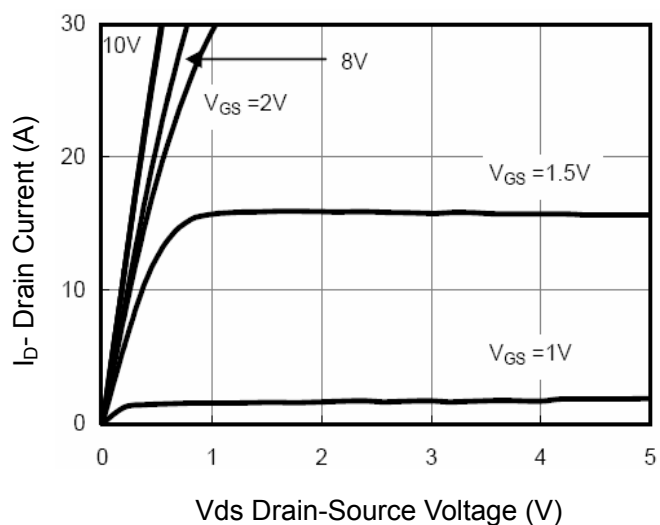


Figure 5 Output Characteristics

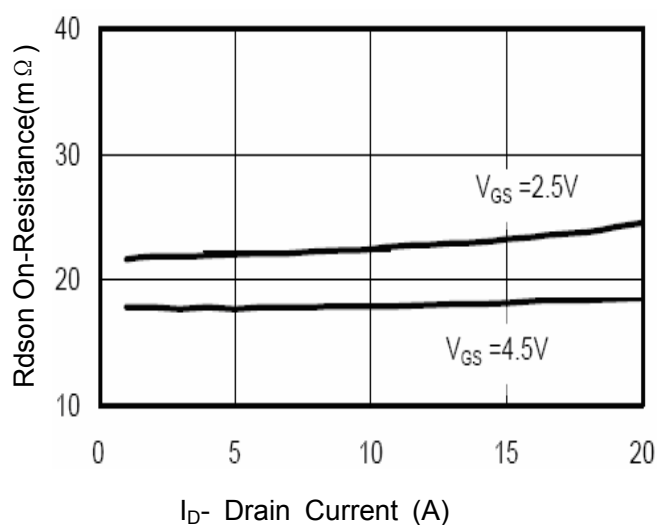


Figure 6 Drain-Source On-Resistance

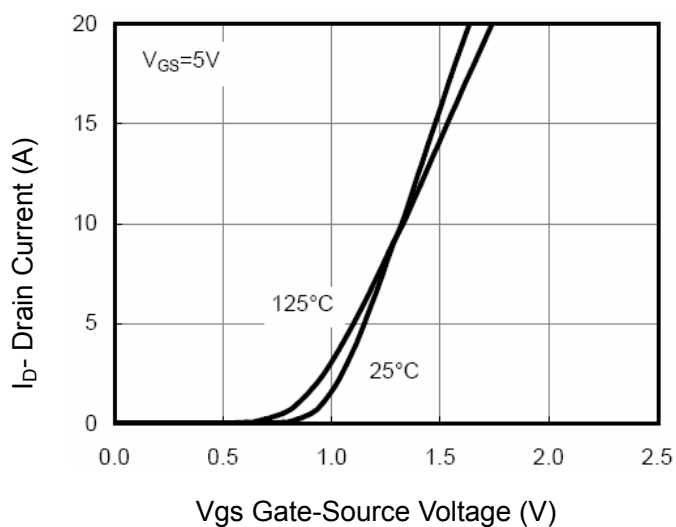


Figure 7 Transfer Characteristics

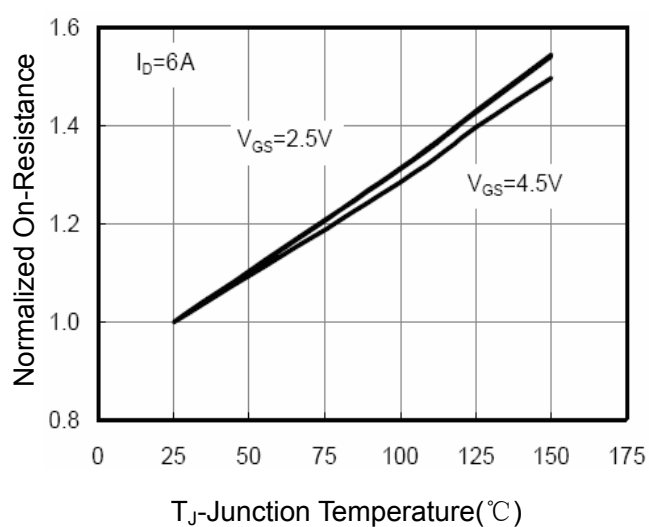


Figure 8 Drain-Source On-Resistance

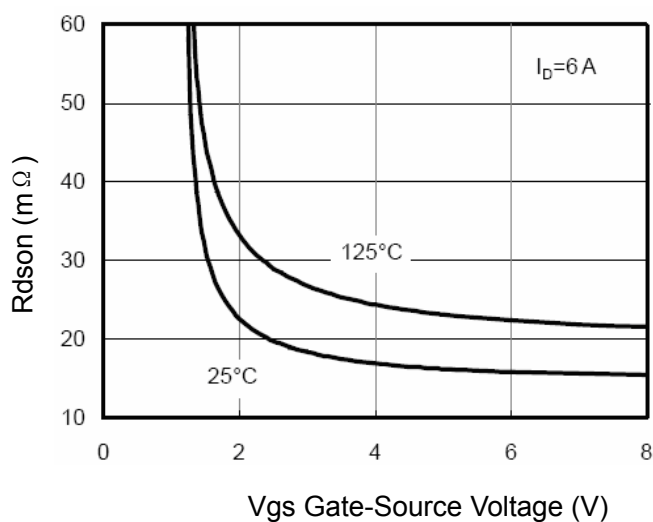
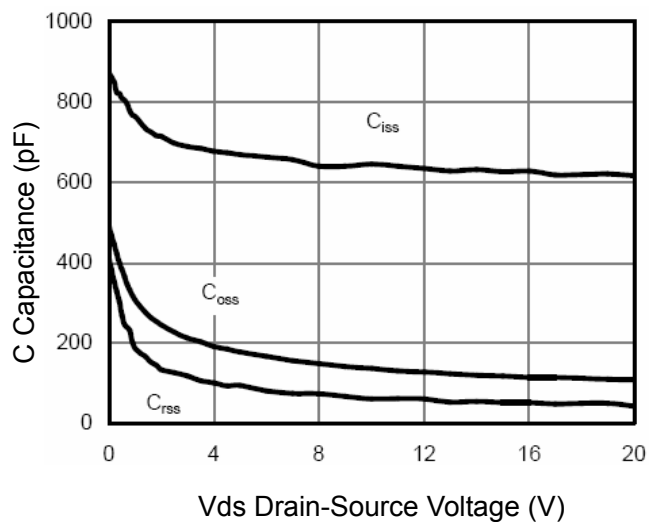
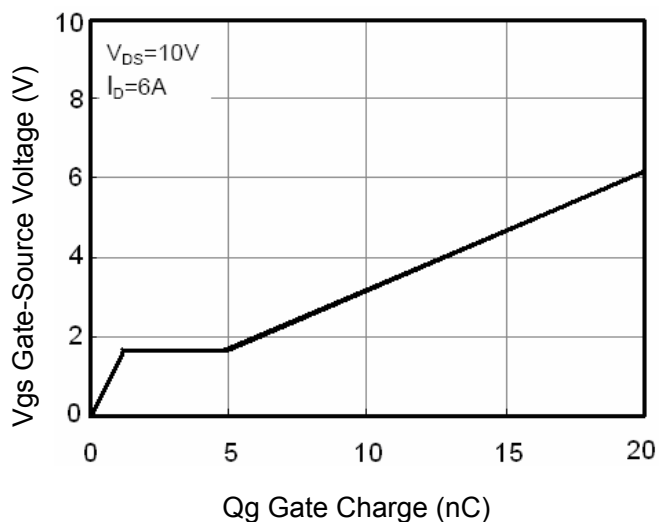

Figure 9 R_{dson} vs V_{GS}

Figure 10 Capacitance vs V_{DS}


Figure 11 Gate Charge

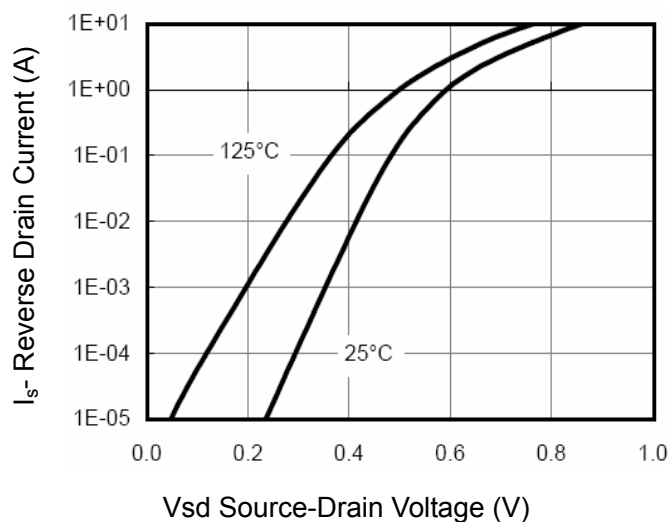


Figure 12 Source- Drain Diode Forward

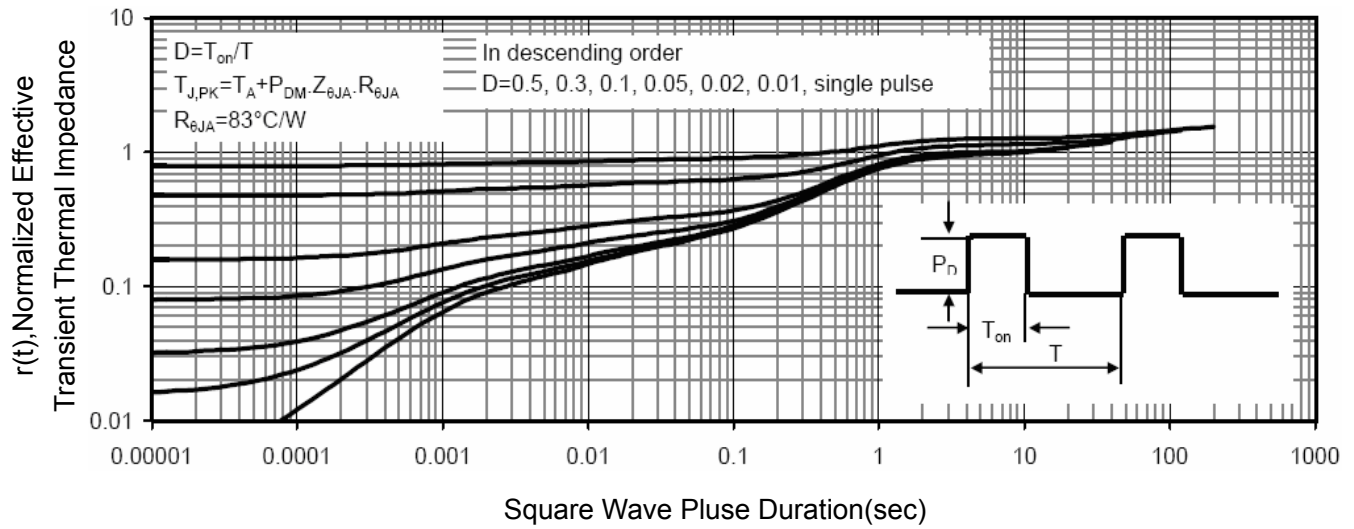
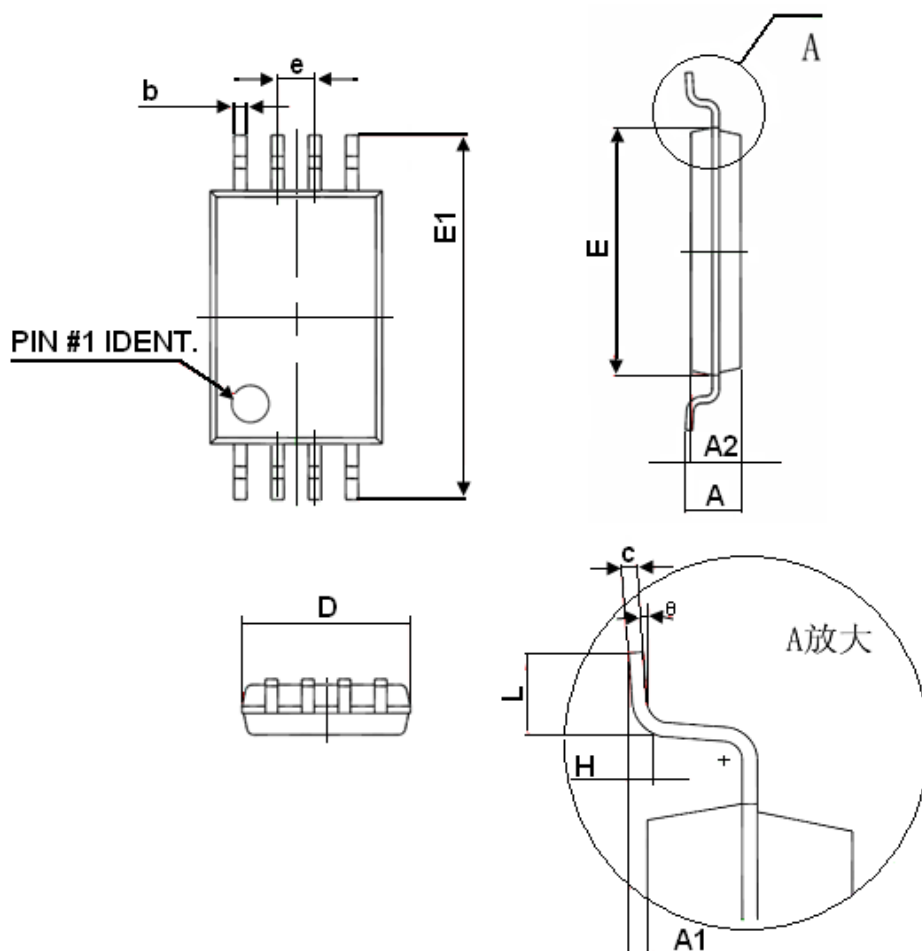


Figure 13 Normalized Maximum Transient Thermal Impedance

Tssop-8 Package Information



Symbol	Dimensions In Millimeters	
	Min	Max
D	2.900	3.100
E	4.300	4.500
b	0.190	0.300
c	0.090	0.200
E1	6.250	6.550
A		1.100
A2	0.800	1.000
A1	0.020	0.150
e	0.65(BSC)	
L	0.500	0.700
H	0.25(TYP)	
θ	1°	7°